

Title (en)

METHOD FOR MANUFACTURING AN ENCAPSULATION DEVICE

Title (de)

HERSTELLUNGSVERFAHREN EINER VORRICHTUNG ZUR VERKAPSELUNG

Title (fr)

PROCÉDÉ DE FABRICATION D'UN DISPOSITIF D'ENCAPSULAGE

Publication

**EP 2782868 B1 20180314 (FR)**

Application

**EP 12775690 A 20121023**

Priority

- EP 11190264 A 20111123
- EP 2012070972 W 20121023
- EP 12775690 A 20121023

Abstract (en)

[origin: EP2597067A1] The elements e.g. cover (4), have a metallization comprising a metal layer (15) that is protected by an intermetallic compound (19), where the elements are partially covered by the metallization. The intermetallic compound is covered by a non-diffused portion (12'), which is made of material having melting point below 250 degree Celsius. The elements are made of ceramic or metal. The metal layer is formed by a body element and comprises a fixing layer (13) that is arranged opposite to the body element. Independent claims are also included for the following: (1) a method for manufacturing an element cooperating with another element for forming an encapsulating device for a component (2) an encapsulation device (3) a method for manufacturing an encapsulation device.

IPC 8 full level

**B81C 1/00** (2006.01)

CPC (source: EP US)

**B81C 1/00269** (2013.01 - EP US); **H03H 3/0072** (2013.01 - US); **H03H 3/02** (2013.01 - US); **H03H 3/04** (2013.01 - US); **H03H 9/02244** (2013.01 - US); **H03H 2003/022** (2013.01 - US); **H03H 2003/026** (2013.01 - US); **H03H 2003/0478** (2013.01 - US); **H03H 2003/0485** (2013.01 - US); **H03H 2003/0492** (2013.01 - US); **Y10T 29/42** (2015.01 - EP US); **Y10T 29/49005** (2015.01 - EP US); **Y10T 29/49574** (2015.01 - EP US)

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

**EP 2597067 A1 20130529**; CN 103958394 A 20140730; CN 103958394 B 20160120; EP 2782868 A1 20141001; EP 2782868 B1 20180314; HK 1200429 A1 20150807; JP 2015503276 A 20150129; JP 5887421 B2 20160316; KR 101521763 B1 20150519; KR 20140099507 A 20140812; US 2014312735 A1 20141023; US 9912313 B2 20180306; WO 2013075901 A1 20130530

DOCDB simple family (application)

**EP 11190264 A 20111123**; CN 201280057764 A 20121023; EP 12775690 A 20121023; EP 2012070972 W 20121023; HK 15100954 A 20150128; JP 2014542749 A 20121023; KR 20147017124 A 20121023; US 201214360403 A 20121023